

CALL FOR PAPERS

TWHM 2019

**13th Topical Workshop on
Heterostructure Microelectronics**



**Hotel Grand Terrace Toyama,
Toyama, Japan
August 26-29, 2019**

<http://www.rciqe.hokudai.ac.jp/twhm2019/>

**Deadline for abstract submission:
April 25, 2019**

Workshop Co-chairs:

Koichi Maezawa (Univ. Toyama)

Joachim Würfl (FBH Berlin)

Patrick Fay (Univ. Notre Dame)



2019 13th Topical Workshop on Heterostructure Microelectronics (TWHM 2019) will be held from 26 to 29, August 2019 at Hotel Grand Terrace Toyama, Toyama, Japan.

This workshop focuses on advanced micro- and nano-electronics based on semiconductor heterostructures. Materials of interest include III-Vs (III-Ns), group IV, oxide semiconductors, 2D layered materials, nano-carbons, and other semiconductors. Various application areas such as power, high-speed and high-frequency applications, and also sensors, solar cells, are in the scope of the workshop. The workshop consists of about 20 invited papers selected from the leading edge of these fields and about 50 contributed papers.

Technical Topics

1. Semiconductor heterostructure materials & characterization
2. Electron devices & process development
3. High frequency, high speed and THz electronics
4. Power electronics
5. Sensors
6. Solar cells
7. Circuit implementation and system applications
8. Manufacturing technology and reliability issues

Program Co-Chairs

Kunio Tsuda (Toshiba Infrastructure Systems & Solutions Corp.)

Guillermo Carpintero (Universidad Carlos III de Madrid)

Srabanti Chowdhury (Stanford University)

Venue

Hotel Grand Terrace Toyama, Toyama, Japan

Toyama is surrounded by 3000-m class mountains and faced to 1000-m depth deep sea. It is blessed with rich nature and tasty foods. It is equally easy to access from major cities, Tokyo, Osaka and Nagoya. Also, Toyama Airport is one of the major airports in Northwest Pacific Region. There are direct flights from Seoul, Dalian, Shanghai, and Taipei. For details, please see the following URL.

<https://foreign.info-toyama.com/en/>



SUBMISSION OF PAPERS

To present a paper, please submit two-page abstract in A4 or Letter size written in English. Your abstract must clearly and concisely state the specific results of your work. Within the two-page limit, the abstract should include appropriate figures and key references. An Application Form should be also sent with the abstract. The example abstract and the application form will be uploaded on the web site.

<http://www.rciqe.hokudai.ac.jp/twhm2019/>

Please send the two-page abstract in PDF format and an application form via e-mail to

twhm-abst@rciqe.hokudai.ac.jp

Abstract Submission Deadline: April 25, 2019

Notification of Acceptance: July 1, 2019